EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3046	(257/678).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/11 18:54
L2	3920	(257/787).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/11 19:24
L3	1869	(257/700).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/11 19:56
L4	704	(257/781).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/11 20:05
L5	2107	(257/786).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/11 20:19
L6	2049	(257/738).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/11 20:32
L7	2392	(257/737).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/11 20:56

EAST Search History

L8	686	(257/684).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/11 21:05
L9	1049	(438/124).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/11 21:14
L10	3641	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/11 21:31
L11	753	(257/e23.054).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/11 21:43
L12	2463	(257/e23.124).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/11 21:44
S1	1	"20010049156"	US-PGPUB	OR	OFF	2005/06/29 15:31
S2	10	"6261864"	US-PGPUB; USPAT	OR	OFF	2005/06/29 15:31
S3	2137	257/786	USPAT	OR	OFF	2006/02/02 15:17
S4	15	"6238952"	USPAT	OR	OFF	2005/06/29 16:10
S5	0	"6025650" and inner with ("Al" or aluminum) and outer with ("Cu" or copper)	USPAT	OR	OFF	2005/06/29 16:56
S6	0	"6025650" and inner same ("Al" or aluminum) and outer same ("Cu" or copper)	USPAT	OR	OFF	2005/06/29 16:56

S7	9	"5656550" and (inner or core or inside) same ("Al" or aluminum) and (outer or outside or coat$3 or plat$3) same ("Cu" or copper)	USPAT	OR	ON	2005/06/29 17:29
S8	6	"5656550" and (inner or core or inside or base or foil or plate) with ("Al" or aluminum) and (outer or outside or coat$3 or plat$3) with ("Cu" or copper)	USPAT	OR	ON	2005/06/29 17:33
S9	21062	(inner or core or inside or base or foil or plate) with ("Al" or aluminum) and (outer or outside or coat$3 or plat$3) with ("Cu" or copper)	USPAT	OR	ON	2005/06/29 17:33
S10	4669	(semiconductor or die or dice or chip or IC) and (inner or core or inside or base or foil or plate) with ("Al" or aluminum) same (outer or outside or coat$3 or plat$3) with ("Cu" or copper)	USPAT	OR	ON	2005/06/29 17:34
S11	4615	(semiconductor or die or dice or chip or IC) and (inner or core or base or foil or plate) with ("Al" or aluminum) same (outer or outside or coat$3 or plat$3) with ("Cu" or copper)	USPAT	OR	ON	2005/06/29 17:34
S12	4584	(semiconductor or die or dice or chip or IC) and (inner or core or base or foil or plate) with ("Al" or aluminum) same (outer or coat$3 or plat$3) with ("Cu" or copper)	USPAT	OR	ON	2005/06/29 17:34
S13	2515	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) same (outer or coat$3 or plat$3) with ("Cu" or copper)) same (substrate or carrier or module or lead or board or film)	USPAT	OR	ON	2005/06/29 17:35
S14	10	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) same (outer or coat$3 or plat$3) with ("Cu" or copper)) same (substrate or carrier or module or lead or board or film) and (substrate or carrier or module or lead or board or film) with curv$3 with (hole or via or open$3 or aperture or cavity)	USPAT	OR	ON	2005/06/29 17:37

S15	163	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) same (outer or coat$3 or plat$3) with ("Cu" or copper)) same (substrate or carrier or module or lead or board or film) and (substrate or carrier or module or lead or board or film) with curv$3	USPAT	OR	ON	2005/06/29 17:37
S16	22	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) same (outer or coat$3 or plat$3) with ("Cu" or copper)) same (substrate or carrier or module or lead or board or film) and (substrate or carrier or module or lead or board or film) same curv$3 with (hole or via or open$3 or aperture or cavity)	USPAT	OR	ON	2005/06/29 17:39
S17	89	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) same (outer or coat$3 or plat$3) with ("Cu" or copper)) same (substrate or carrier or module or lead or board or film) and (substrate or carrier or module or lead or board or film) same (recess$3 or concav$3) with (hole or via or open$3 or aperture or cavity)	USPAT	OR	ON	2005/06/29 17:48
S19	82	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) same (outer or coat$3 or plat$3) with ("Cu" or copper)) same (substrate or carrier or module or lead or board or film) and (curv$3 or concav$3) with (hole or via or open$3 or aperture or cavity) and (substrate or carrier or module or lead or board or film) with (hole or via or open$3 or aperture or cavity)	USPAT	OR	ON	2005/06/29 17:59

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S20	133	(semiconductor or die or dice or chip or IC) and (inner or core or base or foil or plate) with ("Al" or aluminum) same (outer or coat$3 or plat$3) with ("Cu" or copper) and (curv$3 or concav$3) with (hole or via or open$3 or aperture or cavity) and (substrate or carrier or module or lead or board or film) with (hole or via or open$3 or aperture or cavity)	USPAT	OR	ON	2005/06/29 18:03
S21	51	S20 not S19	USPAT	OR	ON	2005/06/29 17:59
S22	14	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) same (outer or coat$3 or plat$3) with ("Cu" or copper)) same (lead near frame or leadframe) and (curv$3 or concav$3) with (hole or via or open$3 or aperture or cavity) and (substrate or carrier or module or lead or board or film) with (hole or via or open$3 or aperture or cavity)	USPAT	OR	ON	2005/06/29 18:04
S23	114	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) same (outer or coat$3 or plat$3) with ("Cu" or copper)) same (lead near frame or leadframe)	USPAT	OR	ON	2005/06/29 18:17
S24	278	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) same (outer or coat$3 or plat$3) with ("Cu" or copper)) same (multi$5)	USPAT	OR	ON	2005/06/29 18:47
S25	270	S24 not S23	USPAT	OR	ON	2005/06/29 18:41
S26	0	(semiconductor or die or dice or chip or IC) and "Cu-Al-Cu" near (multi$5)	USPAT	OR	ON	2005/06/29 18:23
S27	9	(semiconductor or die or dice or chip or IC) and "Cu" near "Al" near "Cu" near (multi$5)	USPAT	OR	ON	2005/06/29 18:24
S28	10	(semiconductor or die or dice or chip or IC) and "Cu" adj "Al" adj "Cu" with (multi$5)	USPAT	OR	ON	2005/06/29 18:28

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S29	290	(semiconductor or die or dice or chip or IC) and "Cu" adj "Al" adj "Cu"	USPAT	OR	ON	2005/06/29 18:28
S30	88	S24 not S23 and (capacitor or passive)	USPAT	OR	ON	2005/06/29 18:41
S31	2	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) same (pad) with ("Cu" or copper)) same (multi$5) and (capacitor or passive)	USPAT	OR	ON	2005/06/29 18:47
S32	2	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) same (pad) with ("Cu" or copper)) same (multi$5 or interposer) and (capacitor or passive)	USPAT	OR	ON	2005/06/29 18:48
S33	8	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) and (pad) with ("Cu" or copper)) same (multi$5 or interposer) and (capacitor or passive)	USPAT	OR	ON	2005/06/29 18:54
S34	240	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) and (pad) with ("Cu" or copper)) and (multi$5 or interposer) and (capacitor or passive)	USPAT	OR	ON	2005/06/29 18:54
S35	9	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) and (pad) with ("Cu" or copper)) and (multi$5 or interposer) and (capacitor or passive) with embedded	USPAT	OR	ON	2005/06/29 19:00
S36	79	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) and (pad) with ("Cu" or copper)) and (multi$5 or interposer or interconnect$3 or redistribut$3) and (capacitor or passive) with (embedded or integrat$3)	USPAT	OR	ON	2005/06/29 19:06

EAST Search History

S37	85	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) and (pad) with ("Cu" or copper)) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (embedded or integrat$3)	USPAT	OR	ON	2005/06/29 19:08
S38	6	S37 not S36	USPAT	OR	ON	2005/06/29 19:07
S39	167	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) and (pad or wiring) with ("Cu" or copper)) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (embedded or integrat$3)	USPAT	OR	ON	2005/06/29 19:17
S40	82	S39 not S37	USPAT	OR	ON	2005/06/29 19:09
S41	895	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) and ("Cu" or copper)) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (embedded or integrat$3)	USPAT	OR	ON	2005/06/29 19:17
S42	141	(semiconductor or die or dice or chip or IC) and ((inner or core or base or foil or plate) with ("Al" or aluminum) and (pad or wiring or coat$3 or plating or plated) with ("Cu" or copper)) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (embedded or integrat$3) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (via or hole or open$3 or aperture or cavity)	USPAT	OR	ON	2005/06/29 19:21
S43	60	S42 not S39	USPAT	OR	ON	2005/06/29 19:18

S44	212	(semiconductor or die or dice or chip or IC) and (inner or core or base or foil or plate) same ("Al" or aluminum) and (pad or wiring or coat$3 or plating or plated) with ("Cu" or copper) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (embedded or integrat$3) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (via or hole or open$3 or aperture or cavity)	USPAT	OR	ON	2005/06/29 19:33
S45	71	S44 not S42	USPAT	OR	ON	2005/06/29 19:22
S46	212	(semiconductor or die or dice or chip or IC) and (inner or core or base or foil or plate) same ("Al" or aluminium) and (pad or wiring or coat$3 or plating or plated) with ("Cu" or copper) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (embedded or integrat$3) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (via or hole or open$3 or aperture or cavity)	USPAT	OR	ON	2005/06/29 19:40
S47	262	(semiconductor or die or dice or chip or IC) and (inner or core or base or foil or plate) same ("Al" or aluminium) and (pad or wiring or coat$3 or plating or plated or electrode) with ("Cu" or copper) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (embedded or integrat$3) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (via or hole or open$3 or aperture or cavity)	USPAT	OR	ON	2005/06/29 19:42

S48	50	S47 not S46	USPAT	OR	ON	2005/06/29 19:40
S49	452	(semiconductor or die or dice or chip or IC) and (inner or core or base or foil or plate) same ("Al" or aluminium) and (pad or wiring or coat$3 or plating or plated or electrode) with ("Cu" or copper) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (embedded or integrat$3) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) with (via or hole or open$3 or aperture or cavity)	USPAT	OR	ON	2005/06/29 19:56
S50	230	S49 not S47	USPAT	OR	ON	2005/06/29 19:43
S51	452	(semiconductor or die or dice or chip or IC) and (inner or core or base or foil or plate) same ("Al" or aluminum) and (pad or wiring or coat$3 or plating or plated or electrode) with ("Cu" or copper) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (embedded or integrat$3) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) with (via or hole or open$3 or aperture or cavity)	USPAT	OR	ON	2005/06/29 20:00
S52	0	(semiconductor or die or dice or chip or IC) and (inner or core or base or foil or plate) same ("Al" or aluminum) and (pad or wiring or coat$3 or plating or plated or electrode) with ("Cu" or copper) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (embedded or integrat$3) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) with (via or hole or open$3 or aperture or cavity)	EPO; JPO	OR	ON	2005/06/29 20:45

S53	273	(semiconductor or die or dice or chip or IC) and (inner or core or base or foil or plate) same ("Al" or aluminum) and (pad or wiring or coat$3 or plating or plated or electrode) with ("Cu" or copper) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) and (capacitor or passive) with (embedded or integrat$3) and (multi$5 or interposer or interconnect$3 or redistribut$3 or carrier or module or substrate or board) with (via or hole or open$3 or aperture or cavity)	US-PGPUB; EPO; JPO	OR	ON	2005/06/29 20:25
S54	0	"5340771".pn.	US-PGPUB; EPO; JPO	OR	ON	2005/06/29 20:26
S55	1	"5340771".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/06/30 15:10
S56	0	("6238952".pn. or "6261864".pn.) and ("Al" or aluminium or aluminum) and ("Cu" or copper) and passive	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/06/29 20:30
S57	2	("6238952".pn. or "6261864".pn.) and ("Al" or aluminium or aluminum) and ("Cu" or copper)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/06/29 20:36
S58	1	"6659145".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/06/29 20:34
S59	3	("6238952".pn. or "6261864".pn. or "5656550".pn.) and ("Al" or aluminium or aluminum) and ("Cu" or copper)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/06/29 20:36
S60	63	(semiconductor or die or dice or chip or IC) and (clad or foil) same ("Al" or aluminum) same (coat$3 or plating or plated) with ("Cu" or copper)	EPO; JPO	OR	ON	2005/06/29 21:13
S61	923	(semiconductor or die or dice or chip or IC) and (clad or foil) same ("Al" or aluminum) same (coat$3 or plating or plated) with ("Cu" or copper)	USPAT	OR	ON	2005/06/29 20:59
S62	2	"5656550" and (clad or foil) same (aluminum) and (coat$3 or plating or plated) with ("Cu" or copper)	USPAT	OR	ON	2005/06/29 20:59

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S63	2	"6646331"	USPAT	OR	OFF	2005/06/29 21:10
S64	0	(semiconductor or die or dice or chip or IC) and (core or inner) with ("Al" or aluminum) and (coat$3 or plating or plated) with ("Cu" or copper) and (curv$3 or arch$3) with (via or hole or open$3 or recess or aperture or cavity)	EPO; JPO	OR	ON	2005/06/29 21:15
S65	0	(semiconductor or die or dice or chip or IC) and ("Al" or aluminum) and (coat$3 or plating or plated) with ("Cu" or copper) and (curv$3 or arch$3) with (via or hole or open$3 or recess or aperture or cavity)	EPO; JPO	OR	ON	2005/06/29 21:14
S66	1	(semiconductor or die or dice or chip or IC) and ("Al" or aluminum) and ("Cu" or copper) and (curv$3 or arch$3) with (via or hole or open$3 or recess or aperture or cavity)	EPO; JPO	OR	ON	2005/06/29 21:14
S67	41	(semiconductor or die or dice or chip or IC) and (core or inner) with ("Al" or aluminum) and (coat$3 or plating or plated) with ("Cu" or copper) and (curv$3 or arch$3) with (via or hole or open$3 or recess or aperture or cavity)	US-PGPUB; USPAT	OR	ON	2005/06/29 21:16
S68	656	(semiconductor or die or dice or chip or IC) and ("Al" or aluminum) and (coat$3 or plating or plated) with ("Cu" or copper) and (curv$3 or arch$3) with (via or hole or open$3 or recess or aperture or cavity)	US-PGPUB; USPAT	OR	ON	2005/06/29 21:52
S69	15	"5442144"	US-PGPUB; USPAT	OR	ON	2005/06/29 21:52
S70	3354	257/678	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/30 16:10

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S71	3674	(semiconductor or die or dice or IC) and (clad$3 or lead) with Aluminum and (coat$3 or plat$3) with ("Cu" or copper)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/30 15:16
S72	1416	(semiconductor or die or dice or IC) and (clad$3 or lead) with Aluminum same (coat$3 or plat$3) with ("Cu" or copper)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/30 15:16
S73	1114	(semiconductor or die or dice or IC) and (clad$3 or lead) with Aluminum same (coat$3 or plat$3) with ("Cu" or copper) with (lead or clad$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/30 15:17
S74	601	(semiconductor or die or dice or IC) and (clad$3 or lead) with Aluminum same (coat$3 or plat$3) with ("Cu" or copper) with (lead or clad$3)	USPAT	OR	ON	2005/06/30 15:36
S75	116	S74 and (passive or capacitor or resistor)	USPAT	OR	ON	2005/06/30 15:27
S76	30	S74 and (passive or capacitor or resistor) with (integrat$3 or embedd$3)	USPAT	OR	ON	2005/06/30 15:27
S77	44	(semiconductor or die or dice or IC) and lead same capacitor with die near pad	USPAT	OR	ON	2005/06/30 15:37
S78	1	"6077727".pn.	USPAT	OR	OFF	2005/06/30 15:52
S79	3160	257/787	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/30 17:55
S80	1114	257/781	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/30 17:55
S81	3	("5543663" | "5869894" | "6404049").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/02 15:11
S82	0	("6646331").URPN.	USPAT	OR	OFF	2006/02/02 13:28

S84	2753	(257/678).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 15:36
S85	3755	(257/787).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/02 15:36